## Tact Switch Series (6x3.5mm)

TS6301E $\square$

## Part Number

| Model No. | High (L) | Embossing |
| :---: | :---: | :---: |
| TS6301E | 4.3 | With |
| TS6301EA | 5.0 | With |
| TS6301NE | 4.3 | Without |
| TS6301NEA | 5.0 | Without |

Dimensions

P.C.B LAYロU
(1) $\longrightarrow$ (3)

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## TACTING SWITCH SPECIFICATION

## 1. GENERAL

1.1 Scope This specification covers the requirements for single key switches which have no keytop(TACT SWITCHES : MECHANICAL CONTACT).
1.2 Operating Temperature Range
-20 to $70^{\circ} \mathrm{C}$ (normal humidity, normal press.)
1.3 Storage Temperature Range
-30 to $80^{\circ} \mathrm{C}$ (normal humidity, normal press.)
1.4 Test Conditions

Tests and measurements shall be made in the following standard conditions unless otherwise specified:
Normal temperature (temperature 5 to $35^{\circ} \mathrm{C}$ )
Normal humidity (relative humidity 45 to $85 \%$ )
Normal pressure (pressure 860 to 1060 m bars)
In case any question arises from the judgment made, tests shall be conducted in the following conditions:

| Temperature | $\left(20 \pm 2^{\circ} \mathrm{C}\right)$ |
| :--- | :--- |
| Relative humidity | $(65 \pm 5 \%)$ |
| Pressure | $(860$ to 1060 m bars $)$ |

## 2. APPEARANCE, STYLE, AND DIMENSIONS

### 2.1 Appearance

There shall be no defects that affect the serviceability of the product.
2.2 Style and Dimensions

Shall conform to the assembly drawings.
3. TYPE OF ACTUATION

4. CONTACT ARRANGEMENT | Tactile feedback |
| :---: |

> (Details of contact arrangement are given in the assembly drawings.)
5. MAXIMUM RATINGS $\quad \mathrm{DC} \quad \underline{12} \mathrm{~V} \quad \underline{50} \mathrm{~mA}$

|  | PART NO: TS6301E |  |
| :--- | :--- | :--- |
|  |  |  |

## TACTING SWITCH SPECIFICATION

## 6. PERFORMANCE

### 6.1 Electrical



### 6.2 Mechanical



### 6.3 Environmental




## TACTING SWITCH SPECIFICATION

## 7. Switch Handling Precautions

7.1 In case an automatic flow soldering apparatus is used for soldering, adhere to the following conditions:

| Item | Soldering condition |
| :--- | :--- |
| 7.1.1. Preheat Temperature | $100^{\circ} \mathrm{C}$ max <br> (Ambient temperature of printed circuit board on <br> its soldering side) |
| 7.1.2. Preheat Time | 45 sec max. |
| 7.1.3. Flux Foaming | To such an extent that fluxes will be kept flush with <br> the printed circuit board's top surface on which <br> components are mounted. <br> Preparatory flux must not be applied to that side of <br> printed circuit board on which components are <br> mounted and to the area where terminals located. |
| 7.1.4. Soldering Temperature | $255^{\circ} \mathrm{C}$ max. |
| 7.1.5. Duration of Solder Immersion | 5 sec. max. <br> 7.1.6. Allowable Frequency of Soldering process |
| 7.2 Other precautions <br> 7.2.1. Following the soldering process, do not try to clean the switch with a solvent or the like. <br> 7.2.2. Safeguard the switch assembly against flux penetration from its topside. <br> 7.2.3. Please have the products keep in close status and the storage time is 90 days guaranty after <br> delivering the goods at most. |  |

